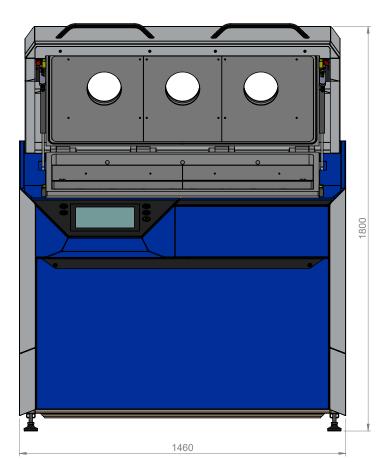
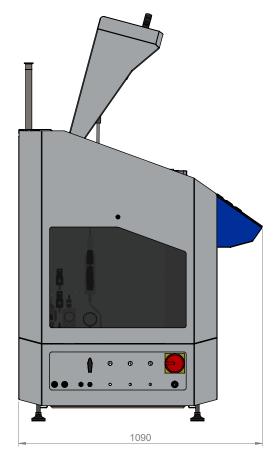


## **VS XL** The next generation of Vacuum Soldering Systems









Technical Data	
Plate size:	1000 x 320 mm <sup>2</sup>
Chamber height:	100 mm
Max. soldering temperature:	350 °C
Heating- / Coolingramp:	1,5 K/s
Max. load:	45 kg
Process atmosphere:	N2
	N <sub>2</sub> H <sub>2</sub> (95/5)
	НСООН
Power supply:	400 V / 64 A
Cooling Water:	20 slm

## Features

Process-Control v	ia separate thermocouples
Graphical overvie	w of process components
Digital manual int	egrated in the software
Maintenance rem	inder
Proposal for chan end of lifetime	ging necessary components at the
Power monitoring	to detect defective heating rods
Monitoring of ene	ergy consumption (Industry 4.0)
Optional manipul	ation inside the chamber
Optional MES pro	tocol: SECS/GEM, OPC-UA, etc.

budatec GmbH, Melli-Beese-Straße 28, 12487 Berlin, phone +4930 632 240 70, www.budatec.de, info@budatec.de budatec reserves the right to make changes in the product specification at any time and without notice. All dimensions in mm. Version 10/21.